

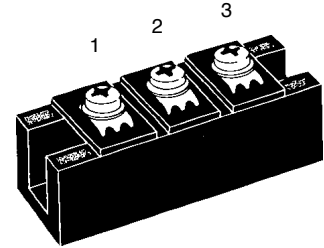
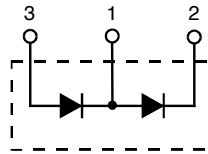
High Power Diode Modules

$$I_{FRMS} = 2 \times 300 \text{ A}$$

$$I_{FAVM} = 2 \times 165 \text{ A}$$

$$V_{RRM} = 800\text{-}1800 \text{ V}$$

V_{RSM} V	V_{RRM} V	Type
900	800	MDD 142-08N1
1300	1200	MDD 142-12N1
1500	1400	MDD 142-14N1
1700	1600	MDD 142-16N1
1900	1800	MDD 142-18N1



Symbol	Test Conditions	Maximum Ratings
I_{FRMS}	$T_{VJ} = T_{VJM}$	300 A
I_{FAVM}	$T_C = 100^\circ\text{C}; 180^\circ \text{ sine}$	165 A
I_{FSM}	$T_{VJ} = 45^\circ\text{C};$ $V_R = 0$	$t = 10 \text{ ms (50 Hz), sine}$ 4700 A $t = 8.3 \text{ ms (60 Hz), sine}$ 5000 A
	$T_{VJ} = T_{VJM}$ $V_R = 0$	$t = 10 \text{ ms (50 Hz), sine}$ 4100 A $t = 8.3 \text{ ms (60 Hz), sine}$ 4300 A
$\int i^2 dt$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	$t = 10 \text{ ms (50 Hz), sine}$ 110 000 A ² s $t = 8.3 \text{ ms (60 Hz), sine}$ 104 000 A ² s
	$T_{VJ} = T_{VJM}$ $V_R = 0$	$t = 10 \text{ ms (50 Hz), sine}$ 84 000 A ² s $t = 8.3 \text{ ms (60 Hz), sine}$ 77 000 A ² s
T_{VJ}		-40...+150 °C
T_{VJM}		150 °C
T_{stg}		-40...+125 °C
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	$t = 1 \text{ min}$ 3000 V~ $t = 1 \text{ s}$ 3600 V~
M_d	Mounting torque (M6) Terminal connection torque (M6)	2.25-2.75/20-25 Nm/lb.in. 4.5-5.5/40-48 Nm/lb.in.
Weight	Typical including screws	120 g

Features

- International standard package
- Direct copper bonded Al_2O_3 -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873

Applications

- Supplies for DC power equipment
- DC supply for PWM inverter
- Field supply for DC motors
- Battery DC power supplies

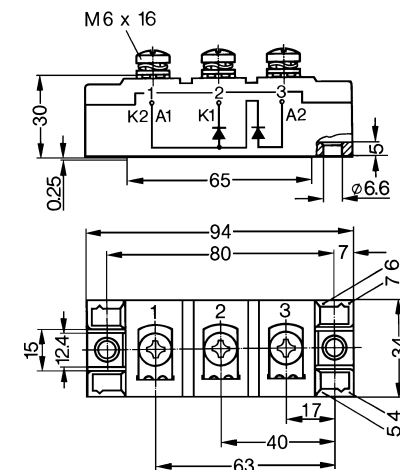
Advantages

- Space and weight savings
- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Symbol	Test Conditions	Characteristic Values
I_R	$T_{VJ} = T_{VJM}; V_R = V_{RRM}$	20 mA
V_F	$I_F = 300 \text{ A}; T_{VJ} = 25^\circ\text{C}$	1.3 V
V_{T0}	For power-loss calculations only	0.8 V
r_T	$T_{VJ} = T_{VJM}$	1.3 mΩ
Q_s	$T_{VJ} = 125^\circ\text{C}; I_F = 300 \text{ A}, -di/dt = 50 \text{ A}/\mu\text{s}$	550 μC
I_{RM}		235 A
R_{thJC}	per diode; DC current	0.21 K/W
R_{thJK}	per module	0.105 K/W
	per diode; DC current	0.31 K/W
	per module	0.155 K/W
d_s	Creepage distance on surface	12.7 mm
d_A	Strike distance through air	9.6 mm
a	Maximum allowable acceleration	50 m/s ²

Data according to IEC 60747 and refer to a single diode unless otherwise stated.
IXYS reserves the right to change limits, test conditions and dimensions

Dimensions in mm (1 mm = 0.0394")



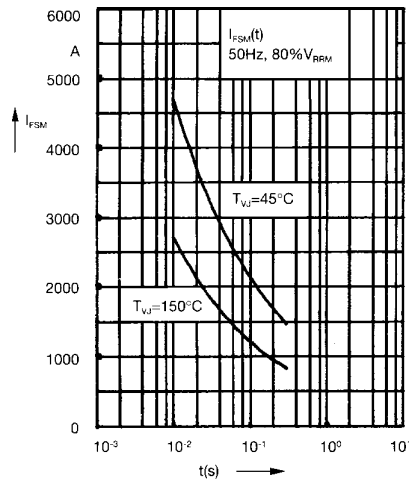


Fig. 1 Surge overload current
 I_{FSM} : Crest value, t : duration

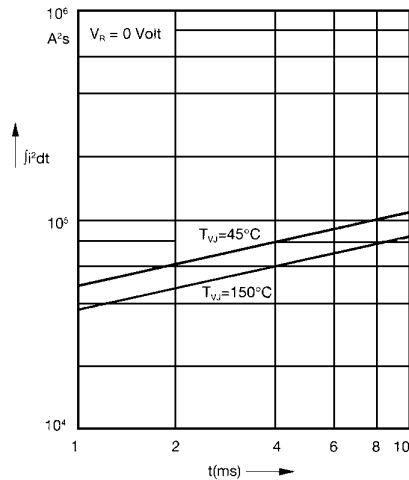


Fig. 2 j^2dt versus time (1-10 ms)

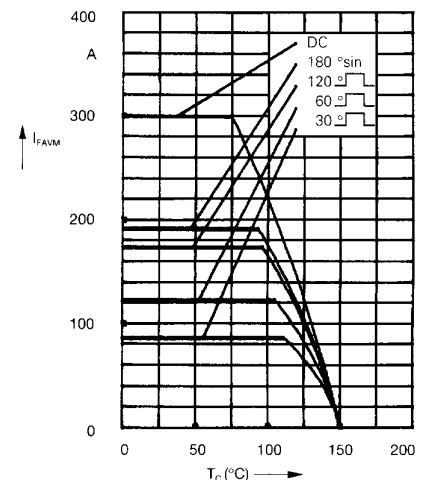


Fig. 2a Maximum forward current
at case temperature

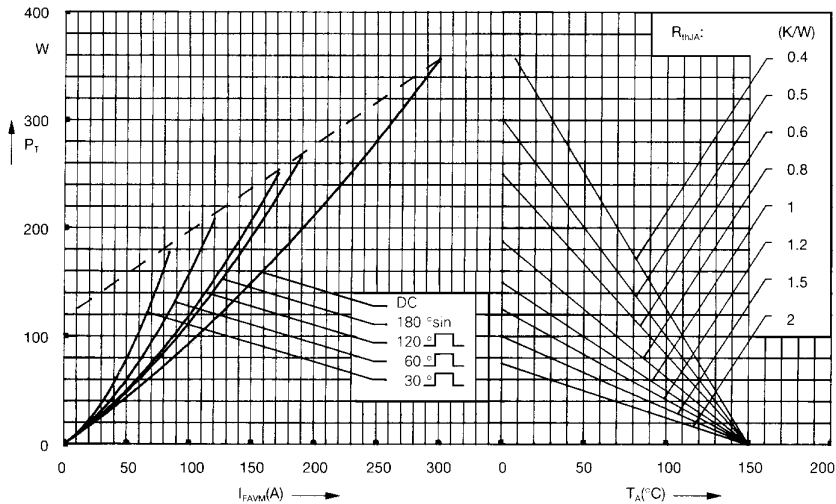


Fig. 3 Power dissipation versus
forward current and ambient
temperature (per diode)

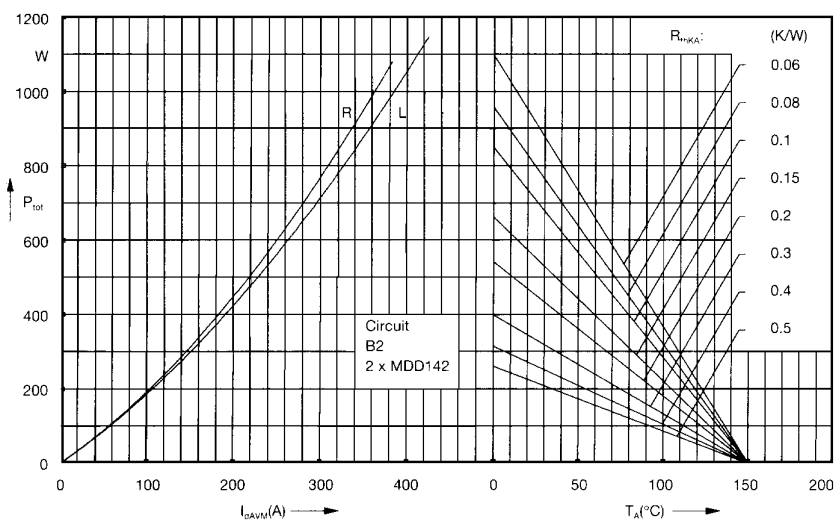


Fig. 4 Single phase rectifier bridge:
Power dissipation versus direct
output current and ambient
temperature
R = resistive load
L = inductive load

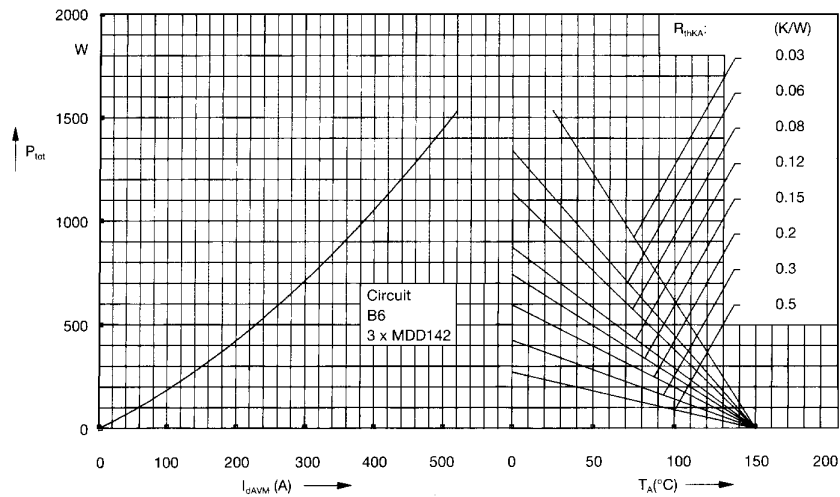


Fig. 5 Three phase rectifier bridge:
Power dissipation versus direct
output current and ambient
temperature

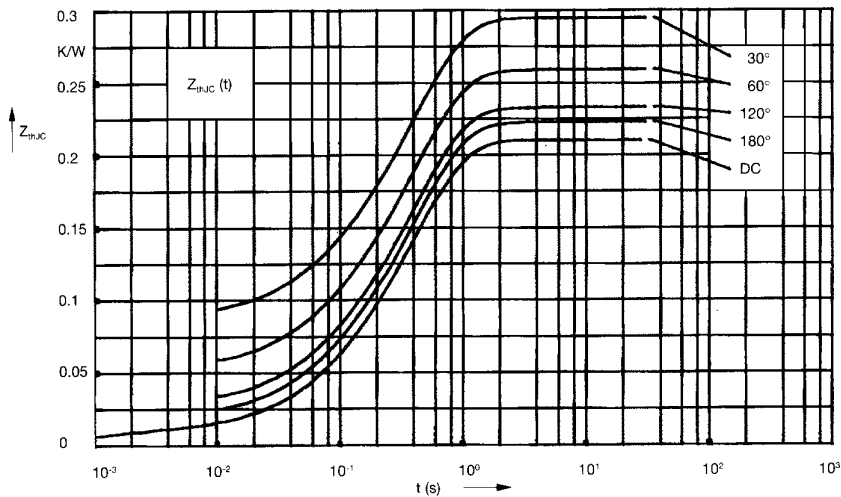


Fig. 6 Transient thermal impedance
junction to case (per diode)

$R_{\theta JC}$ for various conduction angles d :

d	$R_{\theta JC}$ (K/W)
DC	0.210
180°	0.223
120°	0.233
60°	0.260
30°	0.295

Constants for $Z_{\theta JC}$ calculation:

i	$R_{\theta i}$ (K/W)	t_i (s)
1	0.0087	0.001
2	0.0163	0.065
3	0.185	0.4

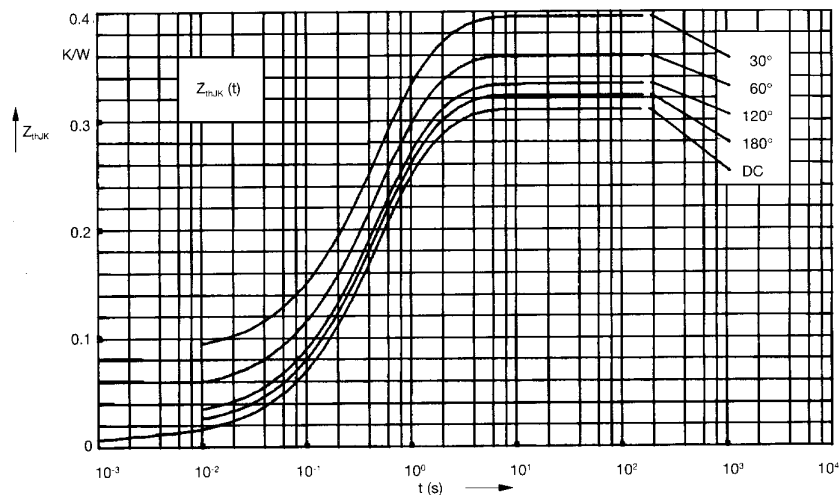


Fig. 7 Transient thermal impedance
junction to heatsink (per diode)

$R_{\theta JK}$ for various conduction angles d :

d	$R_{\theta JK}$ (K/W)
DC	0.31
180°	0.323
120°	0.333
60°	0.360
30°	0.395

Constants for $Z_{\theta JK}$ calculation:

i	$R_{\theta i}$ (K/W)	t_i (s)
1	0.0087	0.001
2	0.0163	0.065
3	0.185	0.4
4	0.1	1.29